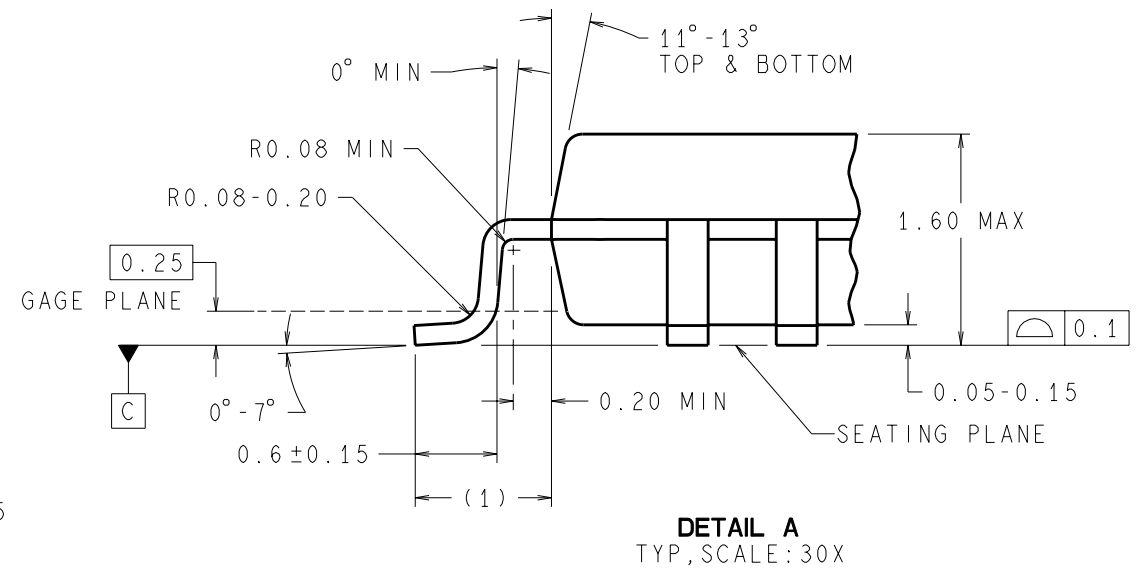
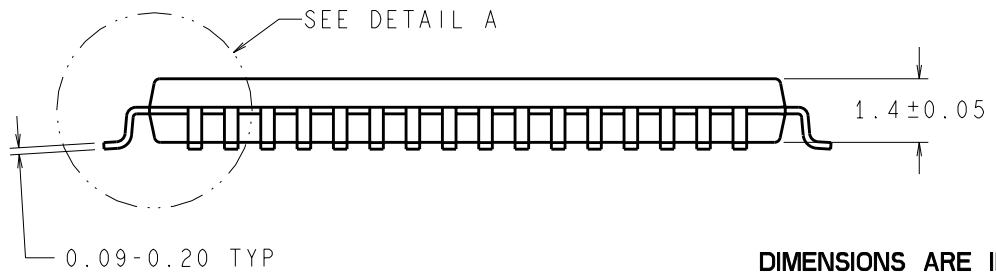
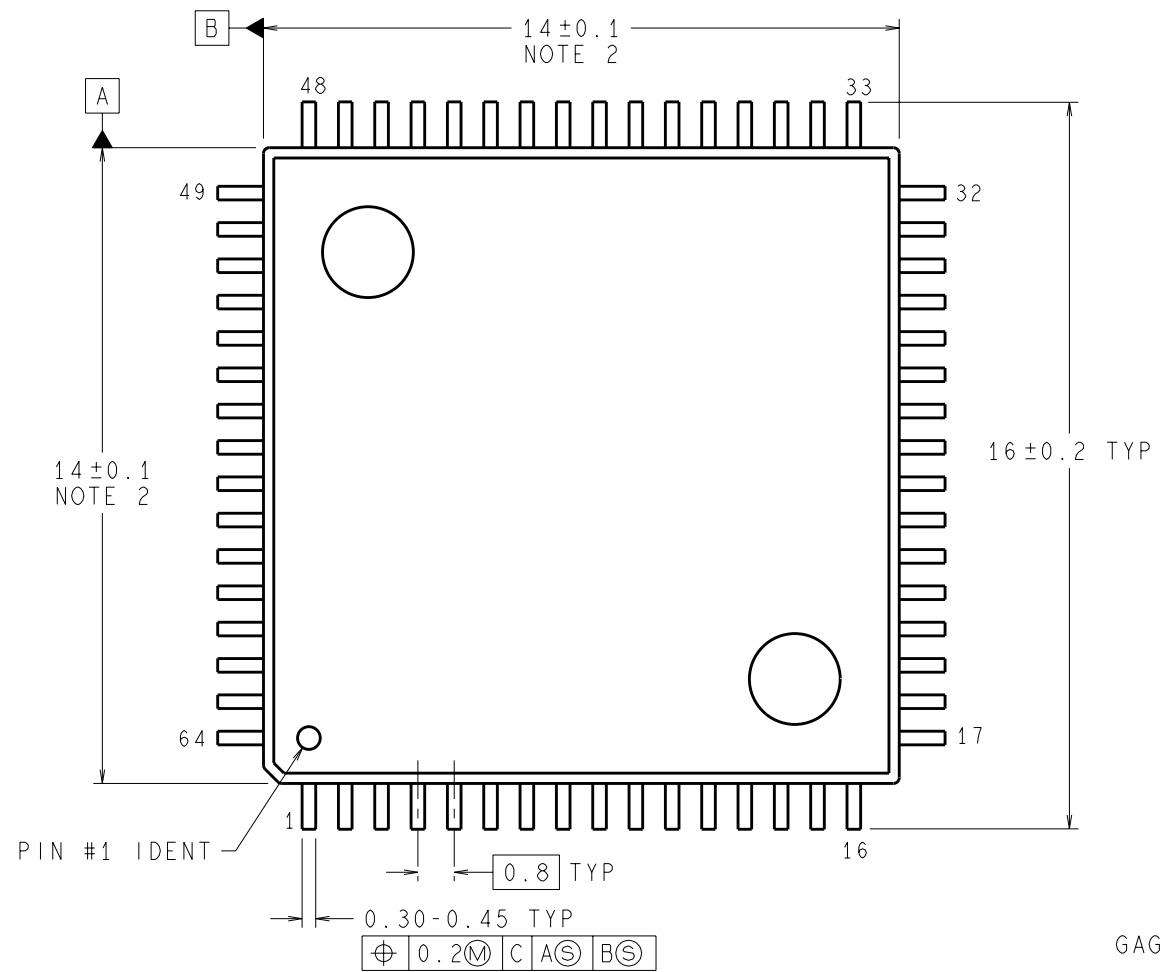


REVISIONS				
LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL	10056	09/23/1993	TL/HJK
B	TITLE: LOFP WAS TOFP; UPDATE NOTE 3; ADD GEOMETRIC TOLERANCE; REDRAW	12317	11/10/1999	TL/RW



DIMENSIONS ARE IN MILLIMETERS

NOTES: UNLESS OTHERWISE SPECIFIED

- STANDARD LEAD FINISH:
7.62 MICROMETERS MINIMUM SOLDER PLATING (85/15)
THICKNESS ON COPPER.
- DIMENSION DOES NOT INCLUDE MOLD PROTRUSION.
MAXIMUM ALLOWABLE MOLD PROTRUSION 0.25mm PER SIDE.
- REFERENCE JEDEC REGISTRATION MS-026, VARIATION BEB,
DATED FEBRUARY 1999.

APPROVALS		DATE		 National Semiconductor 2900 Semiconductor Dr., Santa Clara, CA 95052-8090	
DRAWN T. LEQUANG		11/10/1999			
DFTG. CHK. MARTA SUCHY		11/10/1999			
ENGR. CHK. RANDY WALBERG		11/10/1999		LOFP, JEDEC METRIC, 14 X 14 X 1.4mm, 64 LEAD	
 PROJECTION INCH [MM]		SCALE N/A	SIZE C		
FORMERLY: N/A				SHEET 1 of 1	